

24. (Original) The multiple die electronic system in accordance with claim 21 wherein the substrate is a semiconductor substrate.

25. (Original) The multiple die electronic system in accordance with claim 21 wherein the conductive contacts comprise resilient spring contacts.

26. (Original) The multiple die electronic system in accordance with claim 25 wherein the spring contacts are formed on the first surface of the base IC die and soldered to the conductors on the substrate.

27. (Original) The multiple die electronic system in accordance with claim 21 wherein the conductive contacts comprise:

resilient spring contacts formed on the first surface of the base IC die, and a spring contact socket providing signal paths between the spring contacts and the conductors on the substrate.

28. (Original) The multiple die electronic system in accordance with claim 25 further comprising:

means for holding the base IC die proximate to the substrate so that the spring contacts are compressed against the conductors on the surface of the substrate.

29. (Original) The multiple die electronic system in accordance with claim 21 further comprising:

a second secondary IC die; and
second conductive paths linking the second secondary IC die to the second surface of the base IC die.

30. (Original) The multiple die electronic system in accordance with claim 29 further comprising:

conductive vias for providing signal paths between the first and second surfaces of the base IC die.

31. (Original) The multiple die electronic system in accordance with claim 29 wherein the second conductive paths comprise spring contacts.

32-38 (Withdrawn from Consideration)